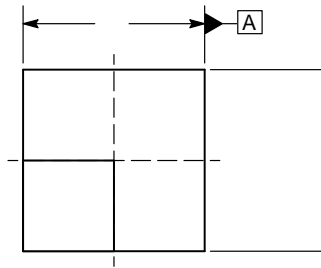UDFN12 3x3, 0.5P
CASE 517AM
ISSUE A

DATE 22 JAN 2015
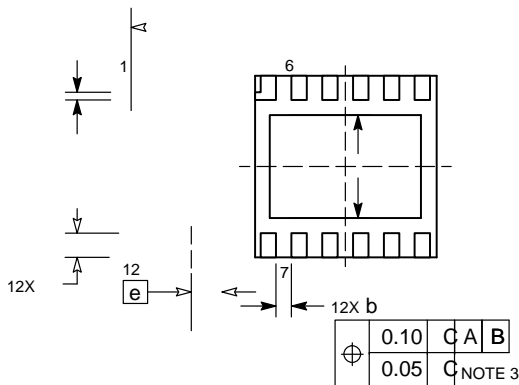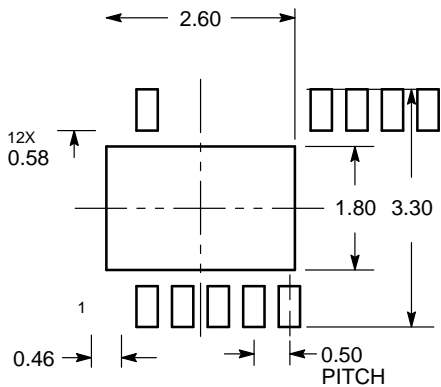
SCALE 4:1

A

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
b	0.20	0.30
D	3.00 BSC	
D2	2.40	2.60
E	3.00 BSC	
E2	1.60	1.80
e	0.50 BSC	
K	0.20	ïïï
L	0.30	0.50

1

6

12

12X

e

7

12X b

⊕ | 0.10 | C A B
0.05 | C NOTE 3

SOLDERING FOOTPRINT*

2.60

12X
0.58

1.80 3.30

1

0.46

0.50
PITCH

*For additional information on our Pb ïFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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